

#### MINI CROWN EDGE | CROWN EDGE

TE Internal #: 1766336-1 Board-to-Board Card Edge Power Connector, 30 Position, 2.5 mm [. 098 in] Centerline, Power & Signal, 12 Power Positions, CROWN EDGE

#### View on TE.com >

#### Connectors > PCB Connectors > Card Edge Connectors > Card Edge Power Connectors



Connector System: Board-to-Board

Number of Positions: 30

Centerline (Pitch): 2.5 mm [.098 in]

Contact Current Rating (Max): 25 A

Circuit Application: Power & Signal

## Features

connectivity

## **Product Type Features**

Connector & Contact Terminates To	Printed Circuit Board
Connector Mates With	Printed Circuit Board
Connector & Housing Type	Receptacle
Connector System	Board-to-Board
Configuration Features	
PCB Mount Orientation	Vertical
Number of Positions	30
Number of Power Positions	12
Number of Signal Positions	18
Number of Dual Positions	6
Electrical Characteristics	
Operating Voltage	250 V
Body Features	
Primary Product Color	Black

**C** For support call+1 800 522 6752

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## **Contact Features**

	04/13/2025
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Jsage Conditions	
Power Contact Centerline	9.7 mm[.381 in]
Connector Height	20 mm[.787 in]
Accepts Card Width	93.34 mm[3.67 in]
Accepts Card Thickness	1.57 mm[.062 in]
Row-to-Row Spacing	6.2 mm[.244 in]
Card Slot Depth	6 mm[.236 in]
Dimensions	
Centerline (Pitch)	2.5 mm[.098 in]
Housing Material	Polyester GF
lousing Features	
PCB Mount Alignment	Without
Mating Alignment	With
PCB Mount Retention Type	Boardlock
Mating Retention	With
PCB Mount Retention	With
Mating Retention Type	Latch
Connector Mounting Type	Board Mount
/lechanical Attachment	
Termination Method to PCB	Surface Mount
ermination Features	
Contact Mating Area Plating Material	Gold (Au)
Contact Current Rating (Max)	25 A
Contact Type	Socket
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Layout	Inline
PCB Contact Termination Area Plating Material Thickness	3.05 μm[120 μin]
Contact Mating Area Plating Material Thickness	.76 μm[29.92 μin]

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#### **Operation/Application**

Circuit Application	Power & Signal
Industry Standards	
Compatible With Agency/Standards Products	CSA, UL
UL Flammability Rating	UL 94V-0
Compatible With Approved Standards Products	CSA 1935071, UL 1977
Packaging Features	
Packaging Quantity	26
Packaging Method	Box & Tray, Package
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2021

### (211) Does not contain REACH SVHC

Not Low Halogen - contains Br or Cl > 900 ppm.

Reflow solder capable to 260°C

#### Halogen Content

Solder Process Capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

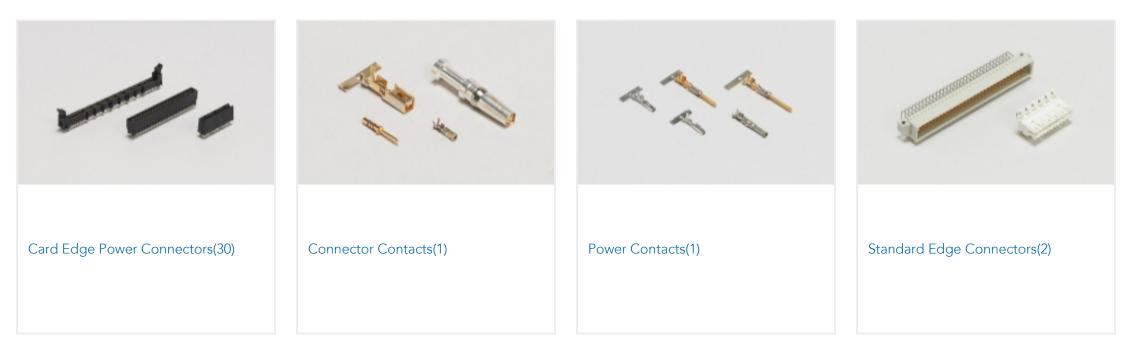
## **Compatible Parts**

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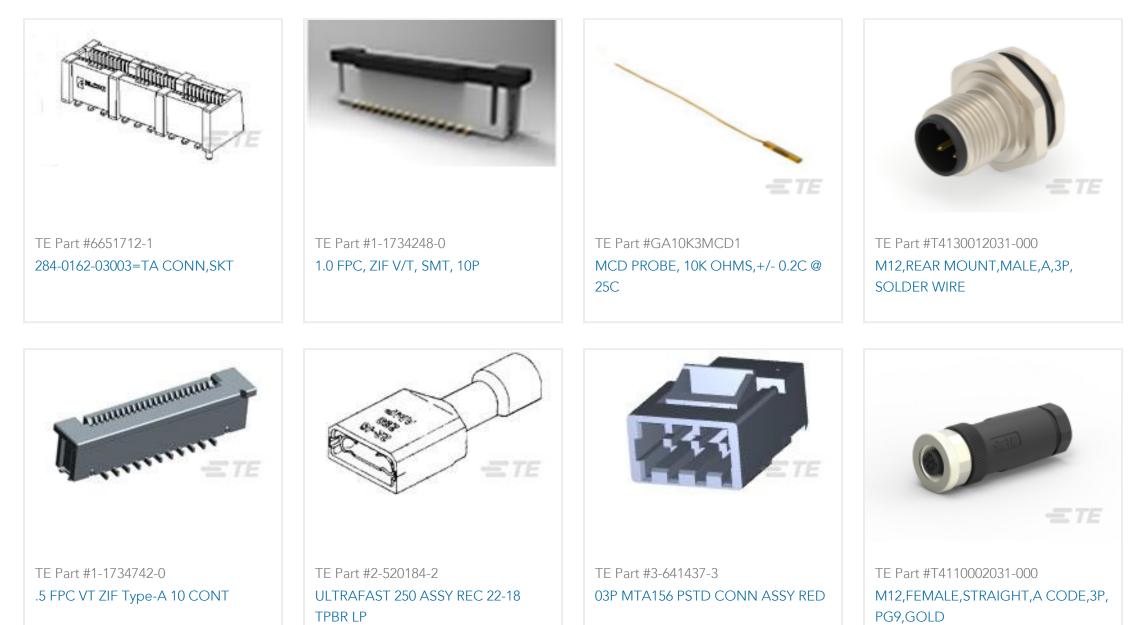




## Also in the Series | CROWN EDGE



# Customers Also Bought



## Documents

## Product Drawings 283-0172-03003=TA CONN,SKT,SMT

English

#### **CAD** Files

3D PDF

3D

Board-to-Board Card Edge Power Connector, 30 Position, 2.5 mm [.098 in] Centerline, Power & Signal, 12 Power Positions, CROWN EDGE



Customer View Model

ENG\_CVM\_CVM\_1766336-1\_B.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_1766336-1\_B.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_1766336-1\_B.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages POWER\_CONNECTORS\_CATALOG\_SEC04\_VRM

English

**Product Specifications** 

**Application Specification** 

English